



June 12, 2012

Micron Boosts DDR3 Offering With 2Gb and 4Gb, 1GHz/DDR3-2133, Delivering Power Efficiency and Speed for High-Performance Networking and Graphics Segments

AMD and LSI Among the Latest Technology Partners

BOISE, Idaho, June 12, 2012 (GLOBE NEWSWIRE) -- Micron Technology, Inc. (Nasdaq:MU), one of the world's leading providers of advanced semiconductor solutions, today introduced a new class of 1GHz, 2-gigabit (Gb) and 4Gb, 30-nanometer (nm) DDR3 devices, strengthening the company's comprehensive DDR3 portfolio. Designed for the high-performance networking and discrete graphics markets, the new devices feature industry-leading low power use while delivering speeds up to 2133 megatransfers per second (MT/s).

Micron supports its customers in highly competitive market segments with a broad portfolio of DRAM and nonvolatile memory devices that meet the demand for high-performance, cost-efficient memory solutions. "Micron has been successful in creating a complete DRAM portfolio, and this product offering rounds out the broadest DRAM offering in the industry," said Mike Howard, senior principal analyst, DRAM and Memory at iSuppli.

Optimized for the demanding, performance-driven discrete graphics and high-speed networking markets, the new DDR3 devices provide the latest SoCs/GPUs with ever-increasing bandwidth required for this space. Industry-leading suppliers AMD and LSI are among the latest technology and IP partners for these products, both having worked closely with Micron throughout the development process. Micron relies on its ecosystem partnerships to deliver greater product reliability and compatibility, which, in turn, optimizes customers' time to market and design costs.

"Massive data growth continues to tax storage and networking equipment, and contending with that growth requires high-performance memory interfaces to meet system bandwidth requirements," said Harold Gomard, SerDes and DDR IP Product Manager, LSI. "Micron's broad memory product line and support for 1GHz DDR3 memory in 2 and 4Gb-based modules enables LSI to meet the needs of enterprise and cloud networking and storage customers."

"We continue to build an aggressive portfolio for the performance-focused graphics market," said Matt Skynner, corporate vice president and general manager, AMD Graphics. "With Micron's new DDR3 devices we expect to drive even more performance."

In addition to components that satisfy both the discrete graphics and networking segments, Micron will offer 2133 megatransfers per second (MT/s) module form factors, including networking-specific ECC UDIMMs.

"High-speed DDR3 will be powering the mainstream graphics and high-performance networking markets in 2012 and beyond. Micron is prepared to support these demanding markets by leveraging our expertise with high-volume, cost-efficient DDR3 products and developing these very high-performance DDR3 devices," said Robert Feurle, vice president of DRAM marketing for Micron. "The combination of our advanced process technology and our commitment to the graphics and high-end computing markets has proven highly successful, and these new 30nm 2Gb and 4Gb DDR3 products will continue to deliver on that promise."

Samples of Micron's new class of high-performance, low-power DDR3 devices are available now, with volume production ramping by summer. For more information, please visit www.micron.com.

Micron Technology, Inc., is one of the world's leading providers of advanced semiconductor solutions. Through its worldwide operations, Micron manufactures and markets a full range of SSDs, DRAM, NAND and NOR flash memory, as well as other innovative memory technologies, packaging solutions and semiconductor systems for use in leading-edge computing, consumer, networking, embedded and mobile products. Micron's common stock is traded on the NASDAQ under the MU symbol. To learn more about Micron Technology, Inc., visit www.micron.com.

The Micron Technology, Inc. logo is available at <http://www.globenewswire.com/newsroom/prs/?pkgid=6950>

©2012 Micron Technology, Inc. All rights reserved. Information is subject to change without notice. Micron and the Micron orbit logo are trademarks of Micron Technology, Inc. This news release contains forward-looking statements regarding the production of DDR3. Actual events or results may differ materially from those contained in the forward-looking statements.

Please refer to the documents Micron files on a consolidated basis from time to time with the Securities and Exchange Commission, specifically Micron's most recent Form 10-K and Form 10-Q. These documents contain and identify important factors that could cause the actual results for Micron on a consolidated basis to differ materially from those contained in our forward-looking statements (see Certain Factors). Although we believe that the expectations reflected in the forward-looking statements are reasonable, we cannot guarantee future results, levels of activity, performance or achievements.

CONTACT: Mary Ellen Ynes

maryellen.ynes@zenogroup.com

650-801-7954